



## Material Content Data Sheet



Sales Product Name	BSC031N06NS3 G			Issued		11. November 2019		
MA#	MA001509928							
Package	PG-TDSON-8-39			Weight*		114.33 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.425	3.87	3.87	38706	38706
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.048	0.04		423	
	non noble metal	copper	7440-50-8	48.352	42.31	42.36	422914	423464
wire	non noble metal	copper	7440-50-8	0.072	0.06	0.06	630	630
encapsulation	organic material	carbon black	1333-86-4	0.078	0.07		680	
	plastics	epoxy resin	-	6.142	5.37		53724	
	inorganic material	silicondioxide	60676-86-0	32.655	28.56	34.00	285620	340024
leadfinish	non noble metal	tin	7440-31-5	1.520	1.33	1.33	13295	13295
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1386	1386
solder	non noble metal	tin	7440-31-5	0.070	0.06		610	
	noble metal	silver	7440-22-4	0.087	0.08		762	
	non noble metal	lead	7439-92-1	3.328	2.91	3.05	29111	30483
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		44	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	noble metal	silver	7440-22-4	0.150	0.13		1312	
	non noble metal	copper	7440-50-8	16.910	14.79	14.93	147905	149409
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.297	0.26	0.26	2599	2603
*deviation	< 10%	Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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